

AMENDMENTS TO THE SPECIFICATION

Amendments to the Abstract

Examiner has objected the abstract of the disclosure because "the subject of this application is an assembly not a method." In view of the newly added claims, which are also directed to the method of filling holes in a wiring board, Applicants believe that the correction requested is no longer necessary.

Amendments to the Detailed Description

1. The changes to the specification are detailed as follows:

In Page 4, line 4, please delete the following text:

[A printed wiring board ("PWB") 30 includes tooling pins 31, tooling pin holes 35, and holes 36 as well as core 33 and copper layers 31 and 32.]

and in its place add the following sentence:

A printed wiring board ("PWB") 30 includes tooling pins 22, holes 36, core 33 and copper layers 31 and 32.

2. In Page 2, Line 27, please amend the following text as follows:

A method of filling holes in a substrate having a plurality of holes of be filled that includes the steps of providing an etched hole-fill stand-off, aligning the stand-off to a tooling plate, aligning the substrate to the stand-off and placing the substrate in contact with the stand-off, and filling the plurality of holes of the substrate.

3. In Page 4, Line 27-28, please amend the following text as follows:

In the preferred embodiment of FIG. 1, PWB 30 rests on top of stand-off 10 but is only bonded to stand-off 10 by pins ~~31~~ 22.

4. In Page 4, Line 28 and Page 5, Line 1, please amend the following text as follows:

Similarly, stand-off 10 preferably rests on tooling plate 23, but is only bonded to tooling plate 23 by alignment pins 21.